SNx4AHCT138 3 线路至 8 线路解码器/多路信号分离器

1 特性

- 输入兼容 TTL 电压
- 专门为高速存储器解码器和数据传输系统设计
- 包含三个使能输入以简化级联和/或数据接收
- 闩锁性能超过 250mA，符合 JESD 17 规范
- ESD 保护性能超过 JESD 22 规范要求
  - ±2000V 人体放电模型 (A114-A)
  - ±1000V 充电器件模型 (C101)

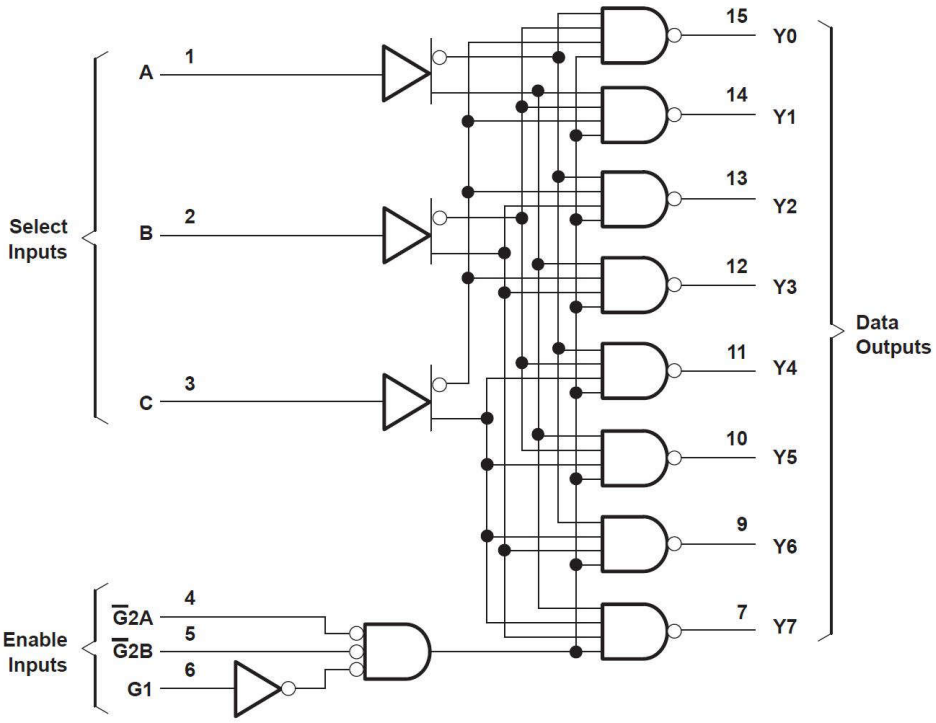
2 说明

AHCT138 3 线至 8 线解码器/多路信号分离器设计用于需要极短传播延迟时间的高性能存储器解码和数据路由应用。在高性能存储器系统中，可使用此解码器来尽可能地消除系统解码的影响。

器件信息

器件型号	封装 (1)	封装尺寸 (2)	本体尺寸 (3)
SNx4AHCT138	RGY（VQFN，16）	4mm x 3.5mm	4mm x 3.5mm
	N（PDIP，16）	19.3 mm × 9.4 mm	19.32mm x 6.35mm
	D（SOIC，16）	9.9 mm × 6 mm	9.90mm x 3.90mm
	NS（SOP，16）	10.2mm x 7.8mm	10.20mm x 5.30mm
	DB（SSOP，16）	6.2mm × 7.8mm	6.20mm x 5.30mm
	PW（TSSOP，16）	5mm × 6.4mm	5.00mm x 4.40mm
	DGV（TVSOP，16）	3.6mm x 6.4mm	3.6mm x 4.4mm

(1) 如需了解更多信息，请参阅机械、封装和可订购信息。
(2) 封装尺寸（长 × 宽）为标称值，并包括引脚（如适用）
(3) 本体尺寸（长 × 宽）为标称值，不包括引脚。



逻辑图（正逻辑）

内容

3 引脚配置和功能

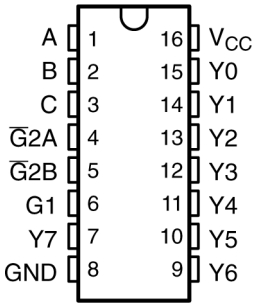


图 3-1. SN54AHCT138 J 或 W 封装；SN74AHCT138 D、DB、DGV、N、NS 或 PW 封装（顶视图）

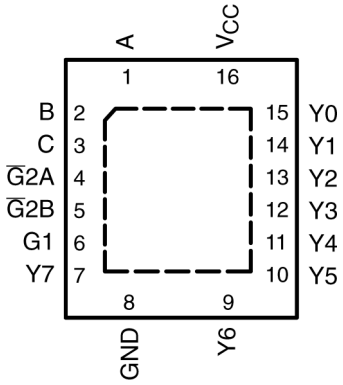
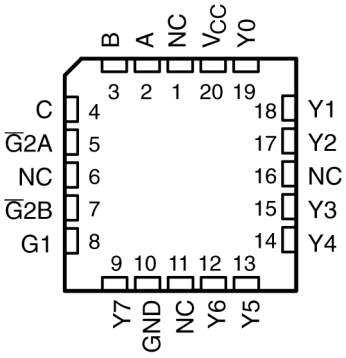


图 3-2. SN74AHCT138 RGY 封装（顶视图）



NC – No internal connection

图 3-3. SN54AHCT138 FK 封装（顶视图）

表 3-1. 引脚功能

引脚		类型(1)	说明
名称	编号		
A	1	I	输入 A
B	2	I	输入 B
C	3	I	输入 C
$\overline{G}$2A	4	I	选通输入 2A，低电平有效
$\overline{G}$2B	5	I	选通输入 2B，低电平有效
G1	6	I	选通输入
Y7	7	O	输出 7
GND	8	G	接地
Y6	9	O	输出 6
Y5	10	O	输出 5
Y4	11	O	输出 4
Y3	12	O	输出 3
Y2	13	O	输出 2
Y1	14	O	输出 1
Y0	15	O	输出 0
V_{CC}	16	P	正电源
散热焊盘(2)		—	散热焊盘

(1) I = 输入，O = 输出，I/O = 输入或输出，G = 接地，P = 电源。
(2) 仅限 BQB 封装

4 规格

4.1 绝对最大额定值

在自然通风条件下的工作温度范围内测得 (除非另有说明) (1)

			最小值	最大值	单位
V_{CC}	电源电压范围		-0.5	7	V
V_I (2)	输入电压范围		-0.5	7	V
V_O (2)	输出电压范围		-0.5	V_{CC} + 0.5	V
I_{IK}	输入钳位电流	(V_I < 0)		-20	mA
I_{OK}	输出钳位电流	(V_O < 0 或 V_O > V_{CC})		±20	mA
I_O	持续输出电流	(V_O = 0 至 V_{CC})		±25	mA
	通过 V_{CC} 或 GND 的持续电流			±75	mA
T_{stg}	贮存温度范围		-65	150	°C

(1) 应力超出“绝对最大额定值”下所列的值可能会对器件造成永久损坏。这些仅为在应力额定值下的工作情况，对于额定值下的器件的功能性操作或者在超出“建议运行条件”下的任何其他情况，在此并未说明。长时间处于绝对最大额定条件下可能会影响器件的可靠性。
(2) 如果遵守输入和输出电流额定值，输入和输出电压可超过额定值。

4.2 ESD 等级

			值	单位
$V_{(ESD)}$	静电放电	人体放电模型 (HBM)，符合 ANSI/ESDA/JEDEC JS-001 标准(1)	±2000	V
		充电器件模型 (CDM)，符合 JEDEC 规范 JESD22-C101(2)	±1000	

(1) JEDEC 文档 JEP155 规定：500V HBM 可实现在标准 ESD 控制流程下安全生产。
(2) JEDEC 文档 JEP157 规定：250V CDM 可实现在标准 ESD 控制流程下安全生产

4.3 建议运行条件

在自然通风条件下的工作温度范围内测得 (除非另有说明) (1)

		SN54AHCT138		SN74AHCT138		单位
		最小值	最大值	最小值	最大值	
V_{CC}	电源电压	1.5	5.5	1.5	5.5	V
V_{IH}	高电平输入电压	2		2		V
V_{IL}	低电平输入电压		0.8		0.8	V
V_I	输入电压	0	5.5	0	5.5	V
V_O	输出电压	0	V_{CC}	0	V_{CC}	V
I_{OH}	高电平输出电流		-8		-8	mA
I_{OL}	低电平输出电流		8		8	mA
$\Delta t/\Delta v$	输入转换上升或下降速率		20		20	ns/V
T_A	自然通风条件下的工作温度范围	-55	125	-40	85	°C

(1) 器件所有的未使用输入必须保持在 V_{CC} 或 GND 以确保器件正常运行。请参阅 TI 应用报告 *CMOS 输入缓慢变化或悬空的影响*，文献编号 SCBA004。

4.4 热性能信息

热性能指标(1)	SN74AHCT138							单位
	DGV (TVSOP)	D (SOIC)	DB (SSOP)	N (PDIP)	NS (SOP)	PW (TSSOP)	RGY (VQFN)	
	16 引脚	16 引脚	16 引脚	16 引脚	16 引脚	16 引脚	16 引脚	
$R_{\theta JA}$ 结至环境热阻	120	93.8	82	67	64	135.9	39	°C/W

(1) 有关新旧热指标的更多信息，请参阅 *半导体和 IC 封装热指标* 应用报告。

4.5 电气特性

在自然通风条件下的建议运行温度范围内测得（除非另有说明）

参数	测试条件	V_{CC}	T_A = 25°C			SN54AHCT138		SN74AHCT138		单位
			最小值	典型值	最大值	最小值	最大值	最小值	最大值	
V_{OH}	I_{OH} = -50 mA	4.5V	4.4	4.5		4.4		4.4		V
	I_{OH} = -8 mA		3.94			3.8		3.8		
V_{OL}	I_{OL} = 50 mA	4.5V			0.1		0.1		0.1	V
	I_{OL} = 8 mA				0.36		0.5		0.44	
I_I	V_I=5.5 V 或 GND	0 V 至 5.5 V			±0.1		±1(1)		±1	mA
I_{CC}	V_I = V_{CC} 或 GND，I_O = 0	5.5 V			4		40		40	mA
ΔI_{CC} (2)	一个输入电压为 3.4V，其他输入电压为 V_{CC} 或 GND	5.5 V			1.35		1.5		1.5	mA
C_i	V_I = V_{CC} 或 GND	5 V		2	10				10	pF

(1) 对于符合 MIL-PRF-38535 标准的产品，此参数未经量产测试（在 V_{CC} = 0V 时）。
(2) 这是每个输入在指定 TTL 电压电平之一而不是 0V 或 V_{CC} 时电源电流的增加情况。

4.6 开关特性

在推荐的自然通风条件下的工作温度范围内测得，V_{CC} = 5V ± 0.5V（除非另有说明）（请参阅图 5-1）

参数	从（输入）	到（输出）	负载电容	T_A = 25°C			SN54AHCT138		SN74AHCT138		单位
				最小值	典型值	最大值	最小值	最大值	最小值	最大值	
t_{PLH}	A、B、C	任一 Y	C_L = 15pF		7.6(1)	10.4(1)	1(1)	12(1)	1	12	ns
t_{PHL}					7.6(1)	10.4(1)	1(1)	12(1)	1	12	
t_{PLH}	G1	任一 Y	C_L = 15pF		6.6(1)	9.1(1)	1(1)	10.5(1)	1	10.5	ns
t_{PHL}					6.6(1)	9.1(1)	1(1)	10.5(1)	1	10.5	
t_{PLH}	$\overline{G}$2A，$\overline{G}$2B	任一 Y	C_L = 15pF		7(1)	9.6(1)	1(1)	11(1)	1	11	ns
t_{PHL}					7(1)	9.6(1)	1(1)	11(1)	1	11	
t_{PLH}	A、B、C	任一 Y	C_L = 50pF		8.1	11.4	1	13	1	13	ns
t_{PHL}					8.1	11.4	1	13	1	13	
t_{PLH}	G1	任一 Y	C_L = 50pF		7.1	10.1	1	11.5	1	11.5	ns
t_{PHL}					7.1	10.1	1	11.5	1	11.5	
t_{PLH}	$\overline{G}$2A，$\overline{G}$2B	任一 Y	C_L = 50pF		7.5	10.6	1	12	1	12	ns
t_{PHL}					7.5	10.6	1	12	1	12	

(1) 对于符合 MIL-PRF-38535 标准的产品，此参数未经量产测试。

4.7 工作特性

V_{CC} = 5V，T_A = 25°C

参数		测试条件		典型值	单位
C_{pd}	功率耗散电容	无负载，	f = 1 MHz	14	pF

4.8 典型特性

T_A = 25°C（除非另外注明）

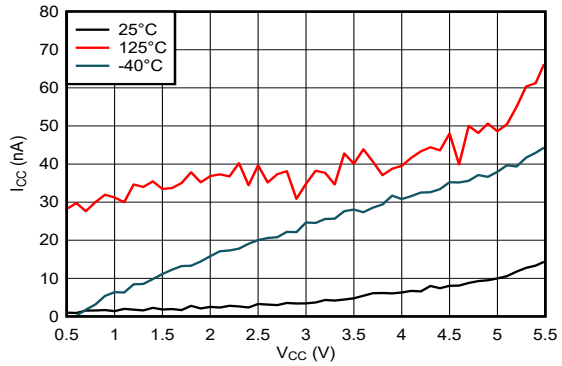


图 4-1. 电源电压两端的电源电流

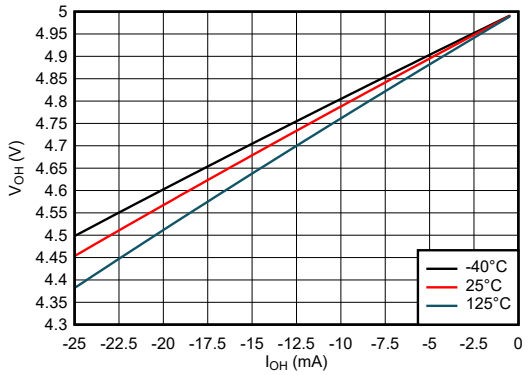


图 4-2. 高电平状态下输出电压与电流间的关系（5V 电源）

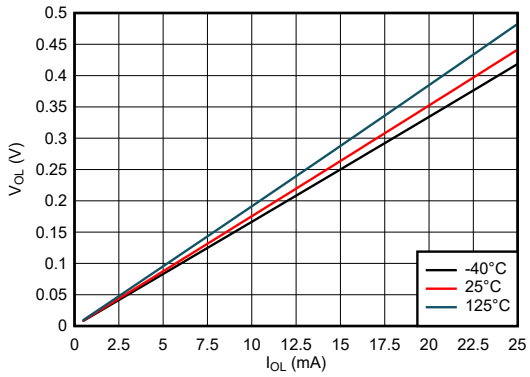
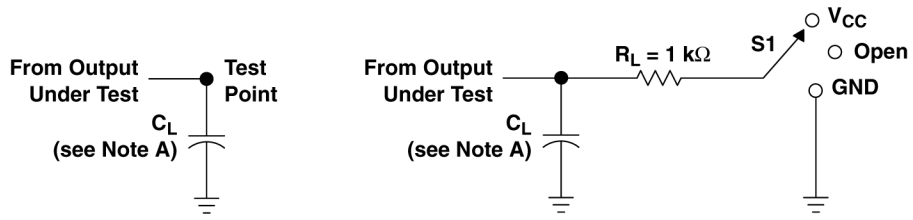


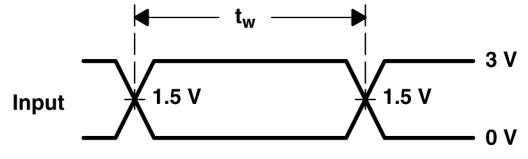
图 4-3. 低电平状态下输出电压与电流间的关系（5V 电源）

5 参数测量信息

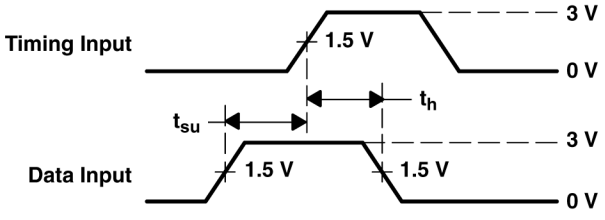


LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

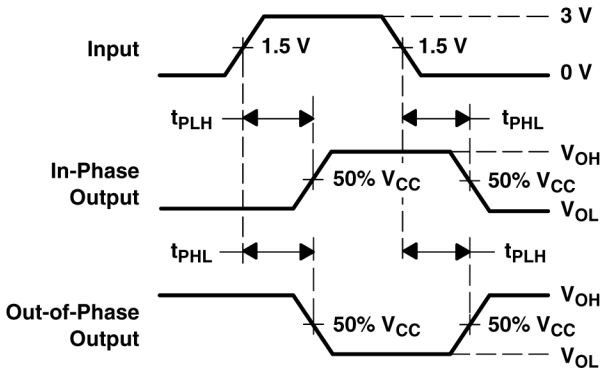
LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS



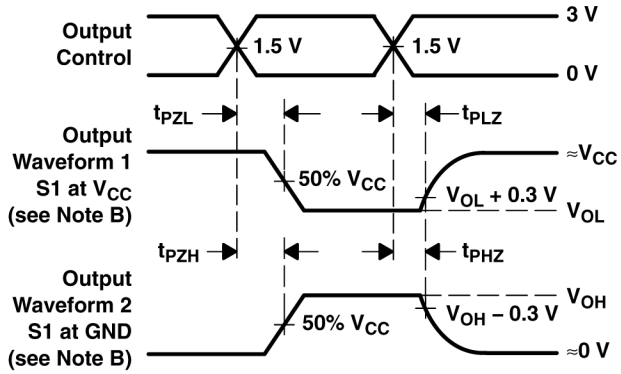
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

A. C_L 包括探头和夹具电容。

B. 波形 1 用于具有内部条件的输出，使得输出为低电平，除非被输出控制禁用。波形 2 用于具有内部条件的输出，使得输出为高电平，除非被输出控制禁用。

C. 所有输入脉冲均由具有以下特性的发生器提供：PRR ≤ 1MHz，Z_O = 50 Ω，t_r ≤ 3 ns，t_f ≤ 3 ns。

D. 一次测量一个输出，每次测量一个输入转换。

E. 并非所有参数和波形都适用于所有器件。

图 5-1. 负载电路和电压波形

测试	S1
t_{PLH}/t_{PHL}	开路
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
漏极开路	V_{CC}

6 详细说明

6.1 概述

与使用快速使能电路的高速存储器一同使用时，该解码器的延迟时间和存储器的使能时间通常小于存储器的典型存取时间。这意味着解码器引起的有效系统延迟可以忽略不计。

二进制选择输入和三个使能输入条件可从八条输出线路中选择其中一条。两个低电平有效使能输入和一个高电平有效使能输入可在扩展时减少对外部门电路或反相器的需要。无需外部反相器即可实现 24 线解码器，并且 32 线解码器只需要一个反相器。使能输入可用作多路信号分离应用的数据输入。

6.2 功能方框图

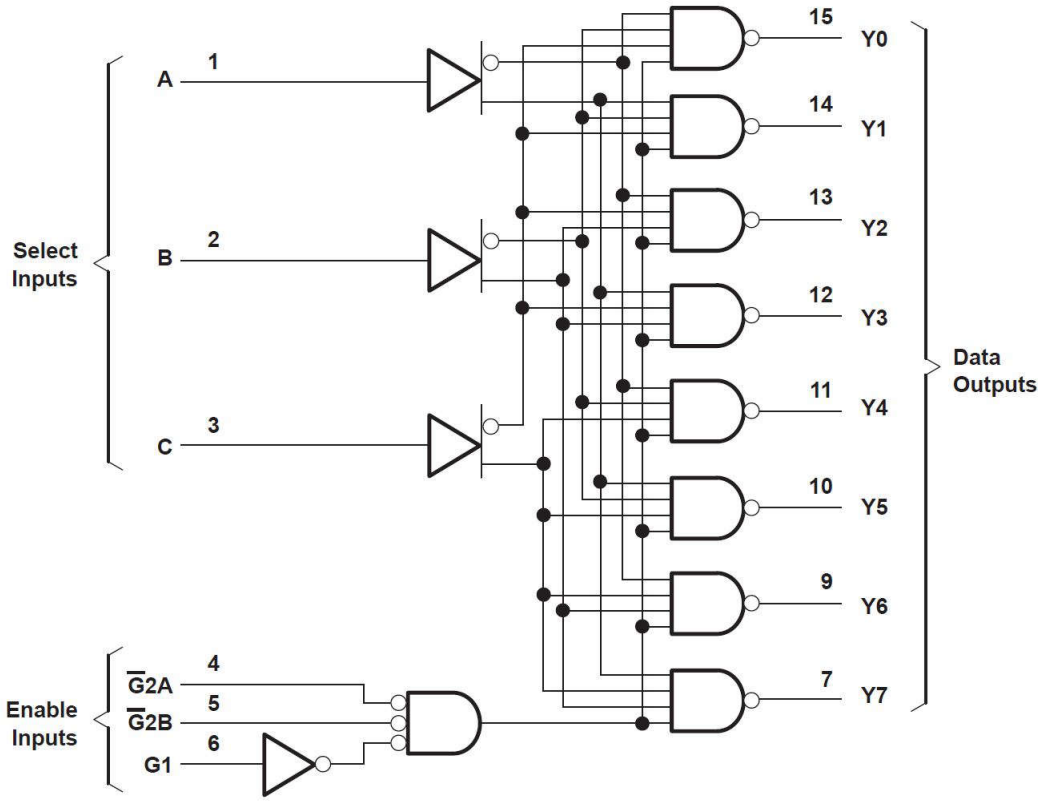


图 6-1. 逻辑图（正逻辑）

6.3 器件功能模式

表 6-1. 功能表

使能输入			选择输入			输出							
G1	$\overline{G2A}$	$\overline{G2B}$	C	B	A	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	H	X	X	X	X	H	H	H	H	H	H	H	H
X	X	H	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	L	H	H	H	H	H	L	H	H	H	H

表 6-1. 功能表（续）

使能输入			选择输入			输出							
G1	$\overline{G2A}$	$\overline{G2B}$	C	B	A	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
H	L	L	H	L	L	H	H	H	H	L	H	H	H
H	L	L	H	L	H	H	H	H	H	H	L	H	H
H	L	L	H	H	L	H	H	H	H	H	H	L	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L

7 应用和实施

备注

以下应用部分中的信息不属于 TI 元件规格，TI 不担保其准确性和完整性。TI 的客户负责确定元件是否适合其用途，以及验证和测试其设计实现以确认系统功能。

7.1 应用信息

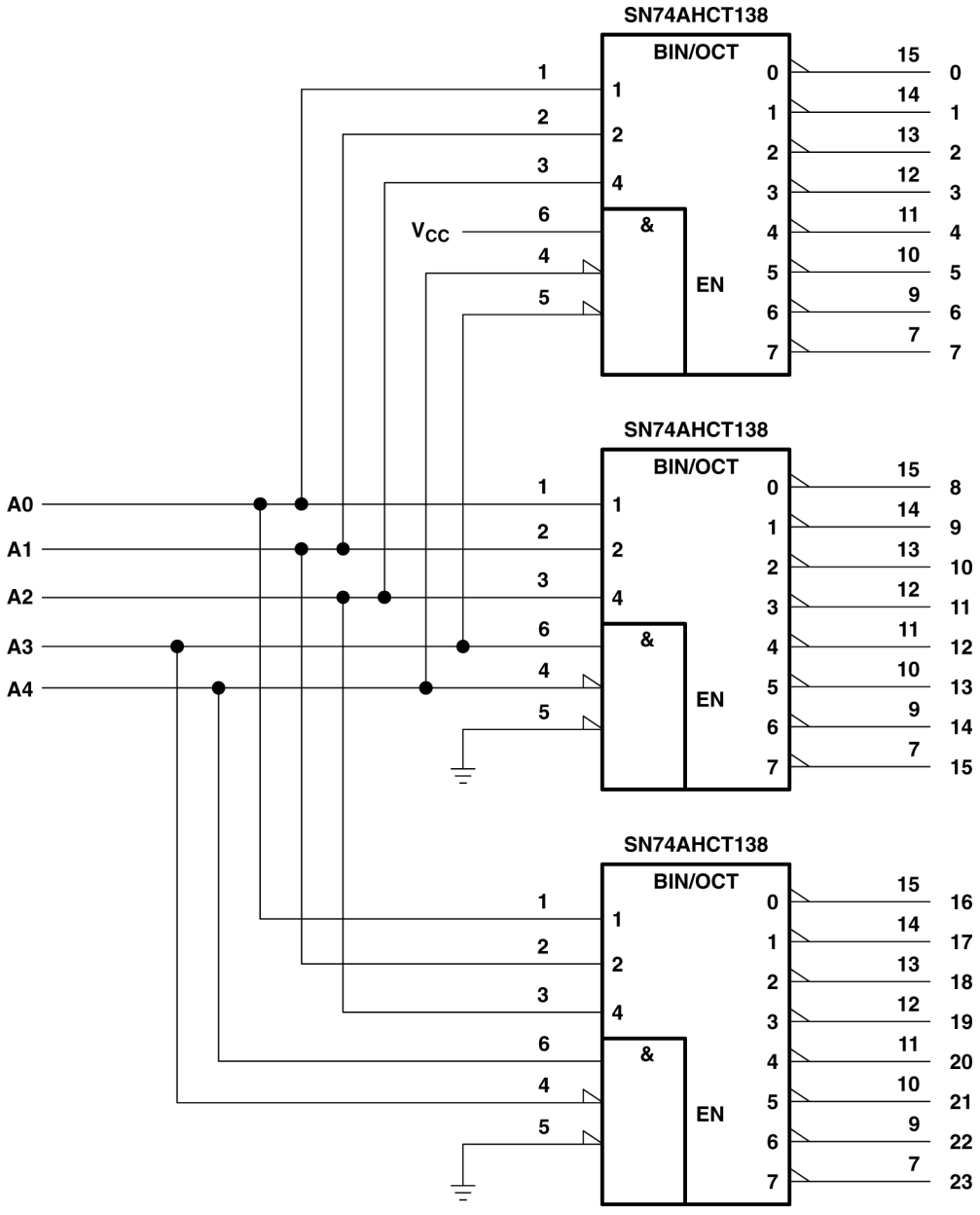


图 7-1. 24 位解码方案

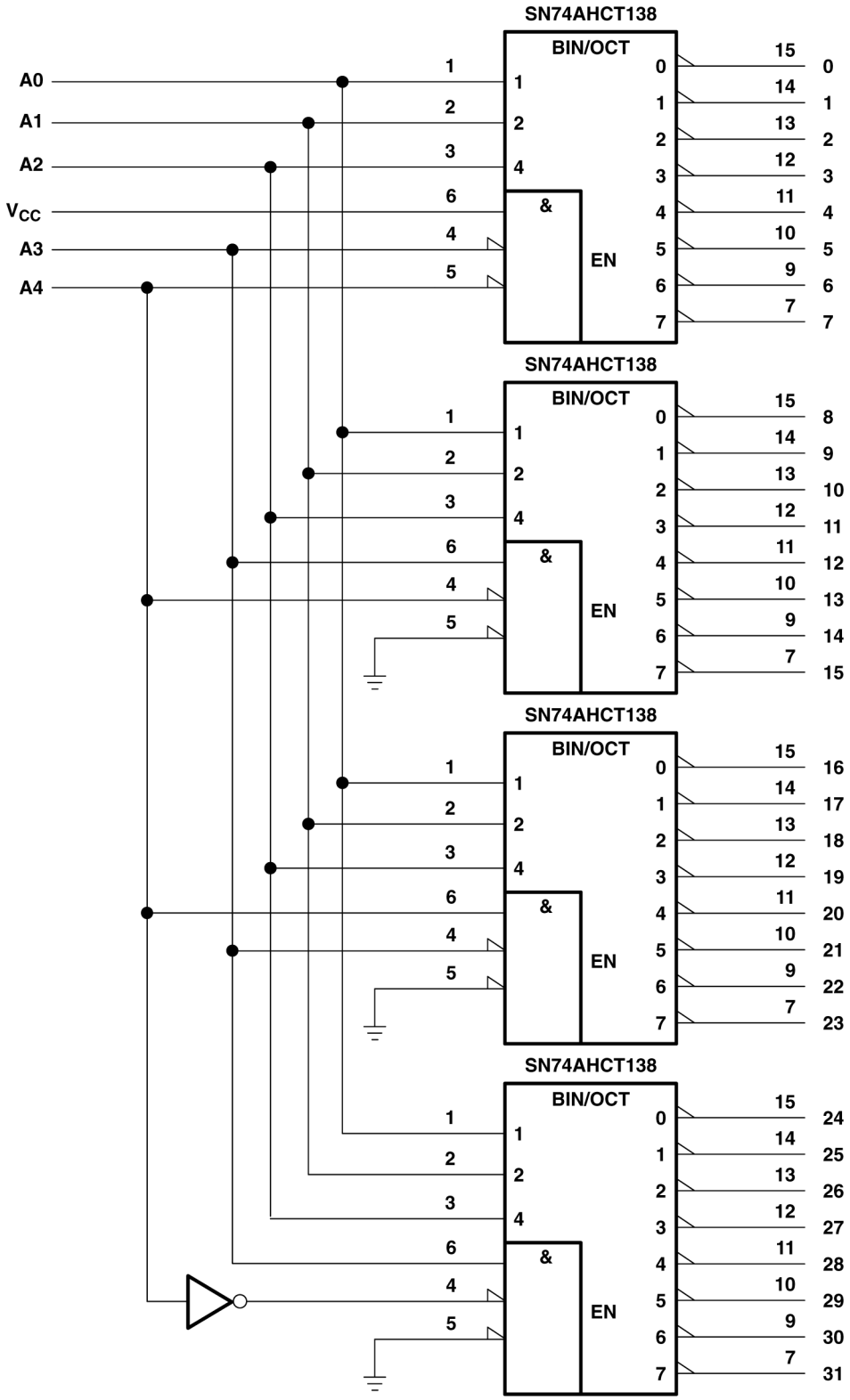


图 7-2. 32 位解码方案

7.2 电源相关建议

电源可以是*建议运行条件*中最小和最大电源电压额定值之间的任何电压。每个 V_{CC} 端子均应具有一个良好的旁路电容器，以防止功率干扰。建议为该器件使用 0.1 µF 电容器。可以并联多个旁路电容器以抑制不同的噪声频率。0.1 µF 和 1 µF 电容器通常并联使用。为了获得最佳效果，旁路电容器必须尽可能靠近电源端子安装。

7.3 布局

7.3.1 布局指南

使用多输入和多通道逻辑器件时，输入不得悬空。在许多情况下，未使用数字逻辑器件的全部或部分功能；例如，仅使用三输入与门的两个输入或仅使用 4 个缓冲门中的 3 个。此类未使用的输入引脚不得悬空，因为外部连接处的未定义电压会导致未定义的操作状态。数字逻辑器件的所有未使用输入必须连接到由输入电压规范定义的逻辑高电平电压或逻辑低电平电压，以防止其悬空。必须应用于任何特定未使用输入的逻辑电平取决于器件的功能。通常，输入连接到 GND 或 V_{CC}，以对逻辑功能更有意义或更方便者为准。

8 器件和文档支持

8.1 文档支持

8.1.1 相关链接

下表列出了快速访问链接。类别包括技术文档、支持和社区资源、工具和软件，以及申请样片或购买产品的快速链接。

表 8-1. 相关链接

器件	产品文件夹	样片 & 购买	技术文档	工具 & 软件	支持 & 社区
SN54AHCT138	点击此处	点击此处	点击此处	点击此处	点击此处
SN74AHCT138	点击此处	点击此处	点击此处	点击此处	点击此处

8.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击*通知* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

8.3 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的使用条款。

8.4 商标

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

8.5 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.6 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

9 修订历史记录

Changes from Revision N (April 2024) to Revision O (July 2024)	Page
• 更新了 R θ JA 值：D = 73 至 93.8，所有值均以 °C/W 为单位	6

Changes from Revision M (July 2003) to Revision N (April 2024)	Page
• 添加了*器件信息* 表、*引脚功能* 表、*ESD 等级* 表、*热性能信息* 表、*器件功能模式*、“应用和实施”部分、*器件和文档支持* 部分以及*机械、封装和可订购信息* 部分	1
• 删除了对机器放电模型的引用	1
• 更新了 R θ JA 值：PW = 108 至 135.9，所有值均以 °C/W 为单位	6

10 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是所指定器件的最新数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。有关此数据表的浏览器版本，请查阅左侧的导航栏。

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9851701Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9851701Q2A SNJ54AHCT 138FK	Samples
5962-9851701QEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9851701QEA SNJ54AHCT138J	Samples
5962-9851701QFA	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9851701QFA SNJ54AHCT138W	Samples
SN74AHCT138D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 85	AHCT138	
SN74AHCT138DBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB138	Samples
SN74AHCT138DGVR	ACTIVE	TVSOP	DGV	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB138	Samples
SN74AHCT138DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT138	Samples
SN74AHCT138N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHCT138N	Samples
SN74AHCT138NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT138	Samples
SN74AHCT138PW	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI	-40 to 85	HB138	
SN74AHCT138PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	HB138	Samples
SN74AHCT138RGYR	ACTIVE	VQFN	RGY	16	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	HB138	Samples
SNJ54AHCT138FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9851701Q2A SNJ54AHCT 138FK	Samples
SNJ54AHCT138J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9851701QEA SNJ54AHCT138J	Samples
SNJ54AHCT138W	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9851701QFA SNJ54AHCT138W	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN54AHCT138, SN74AHCT138 :

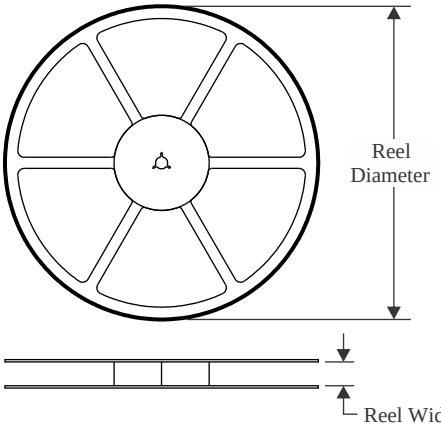
- Catalog : SN74AHCT138
- Enhanced Product : SN74AHCT138-EP, SN74AHCT138-EP
- Military : SN54AHCT138

NOTE: Qualified Version Definitions:

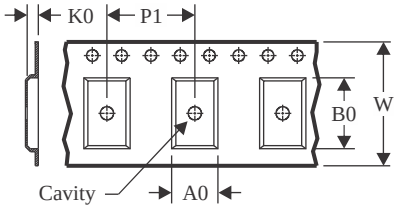
- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

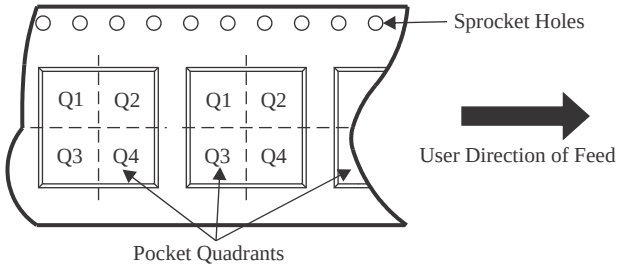


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

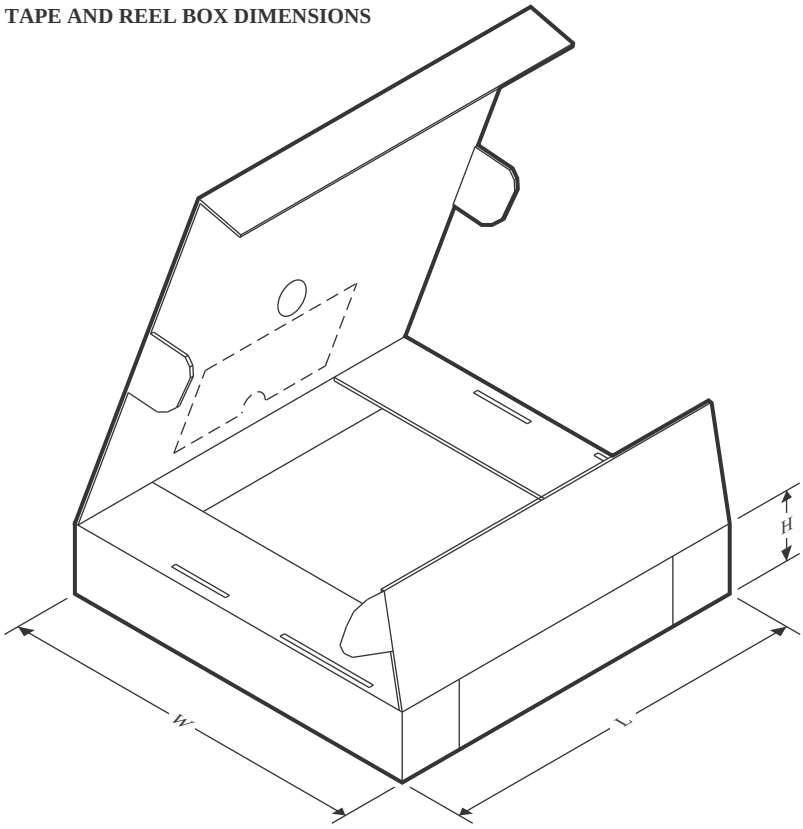
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT138DBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AHCT138DGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AHCT138DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AHCT138DR	SOIC	D	16	2500	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1
SN74AHCT138DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AHCT138NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AHCT138PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT138PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT138RGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

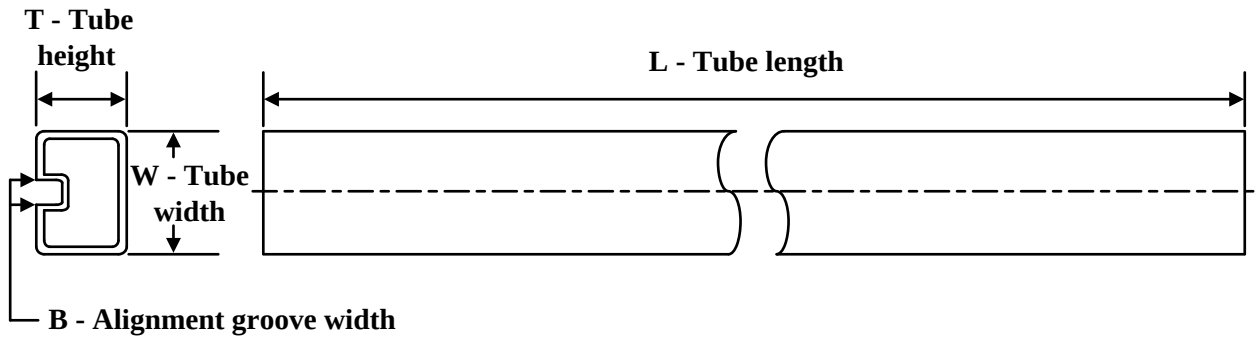
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

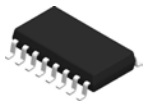
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT138DBR	SSOP	DB	16	2000	356.0	356.0	35.0
SN74AHCT138DGVR	TVSOP	DGV	16	2000	356.0	356.0	35.0
SN74AHCT138DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74AHCT138DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74AHCT138DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74AHCT138NSR	SO	NS	16	2000	356.0	356.0	35.0
SN74AHCT138PWR	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74AHCT138PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74AHCT138RGYR	VQFN	RGY	16	3000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9851701Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9851701QFA	W	CFP	16	25	506.98	26.16	6220	NA
SN74AHCT138N	N	PDIP	16	25	506	13.97	11230	4.32
SN74AHCT138N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54AHCT138FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AHCT138W	W	CFP	16	25	506.98	26.16	6220	NA

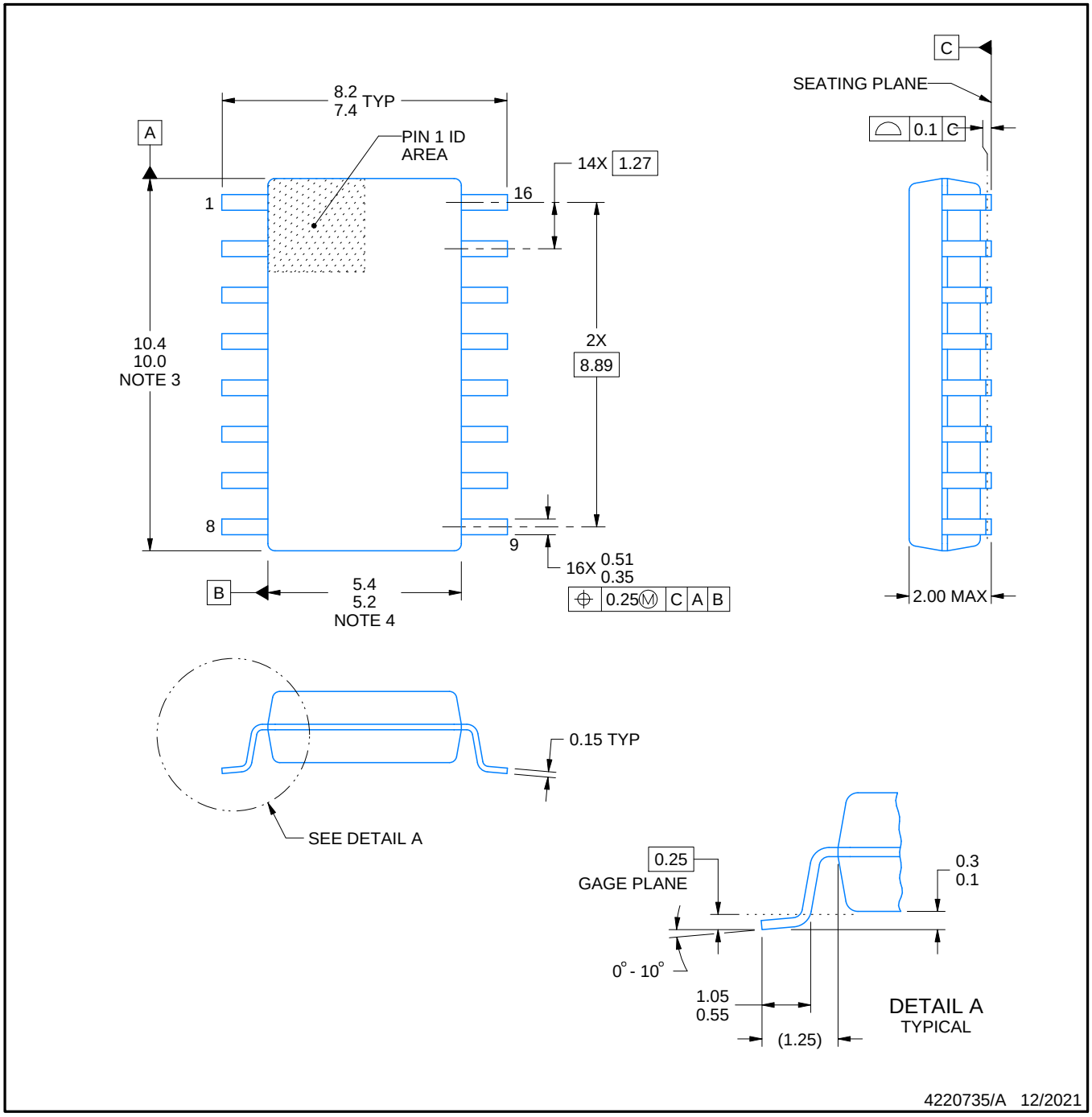


PACKAGE OUTLINE

NS0016A

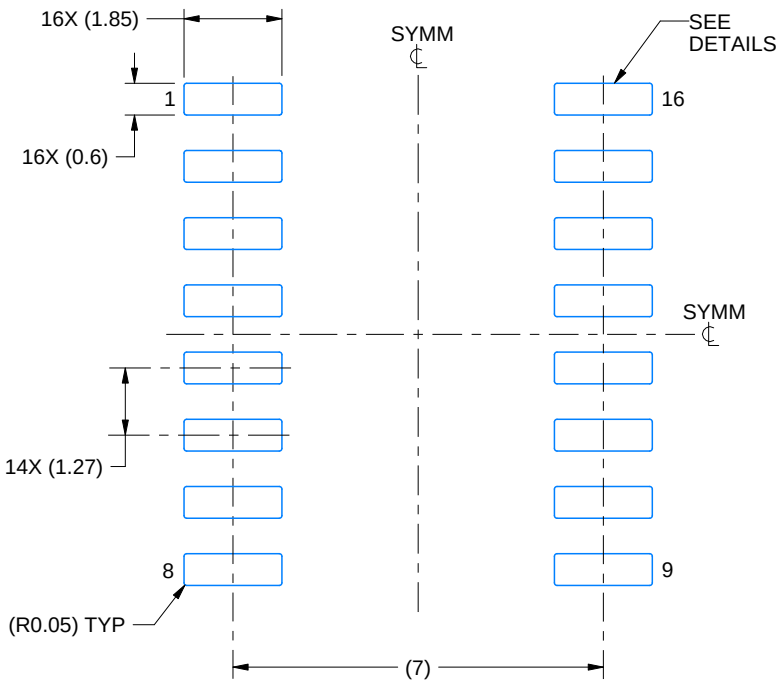
SOP - 2.00 mm max height

SOP

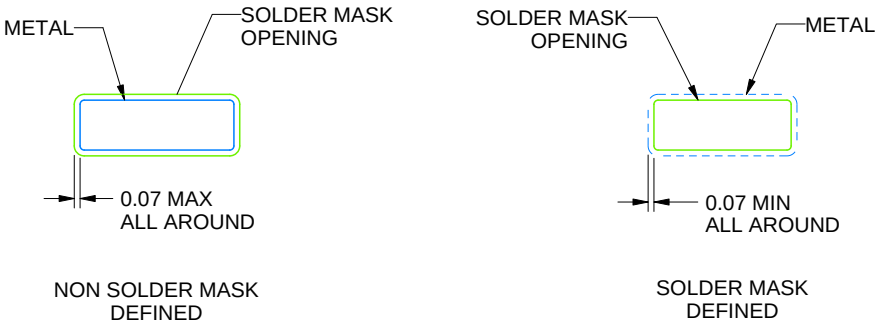


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

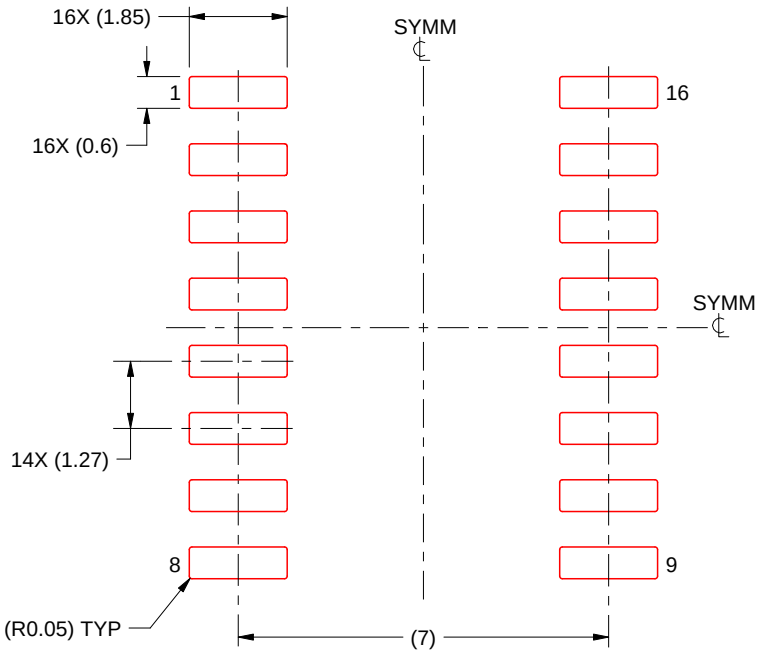
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



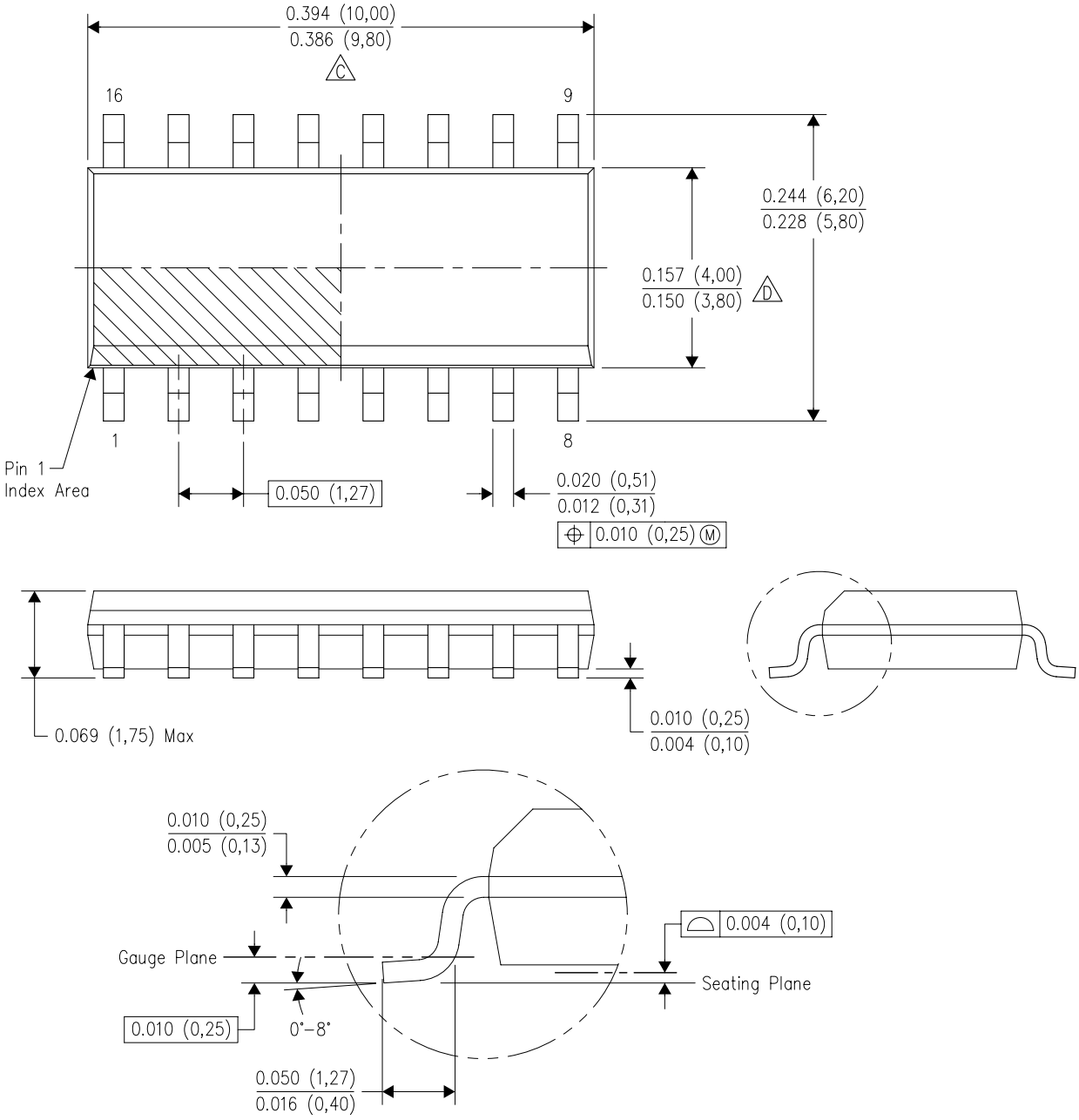
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



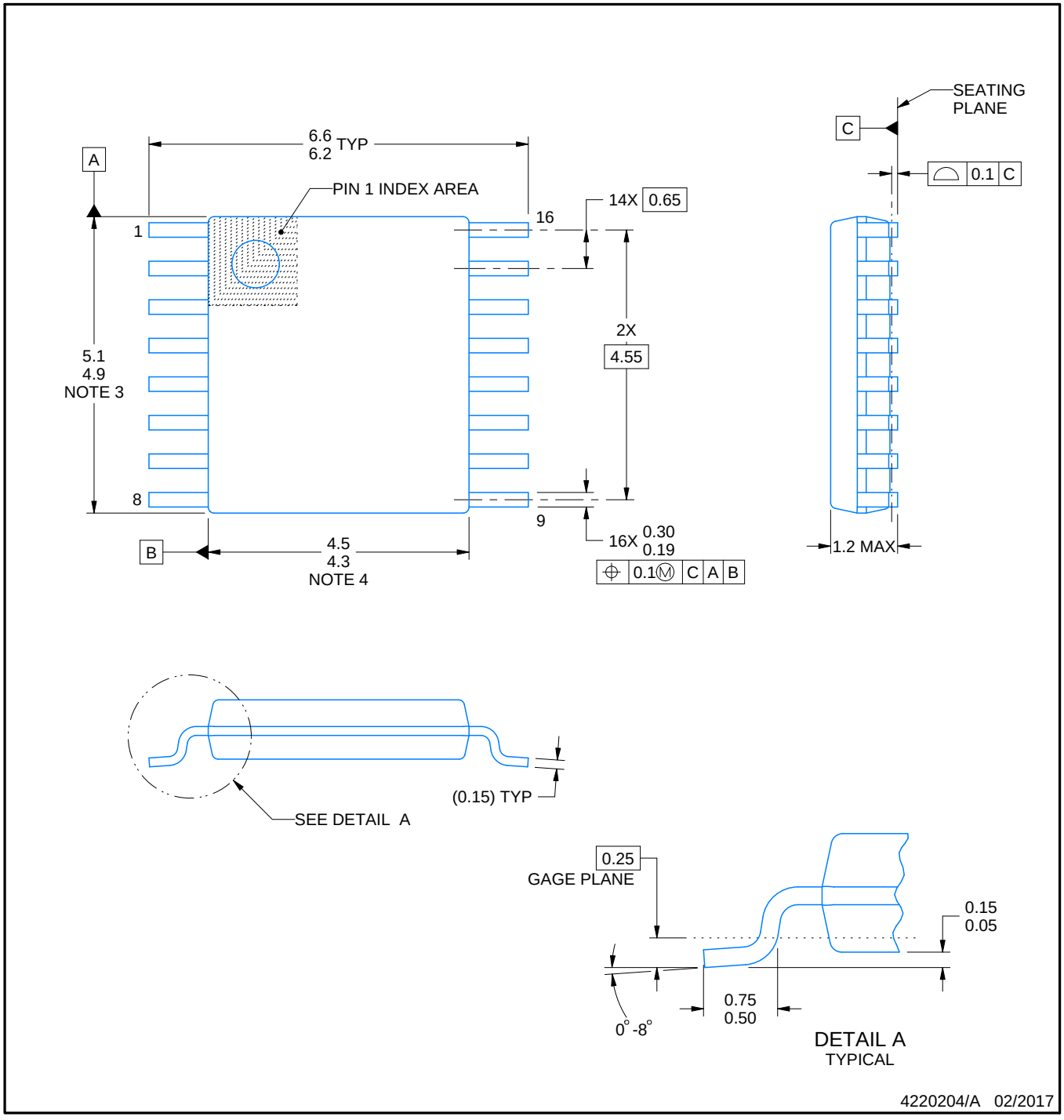
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

PACKAGE OUTLINE

PW0016A

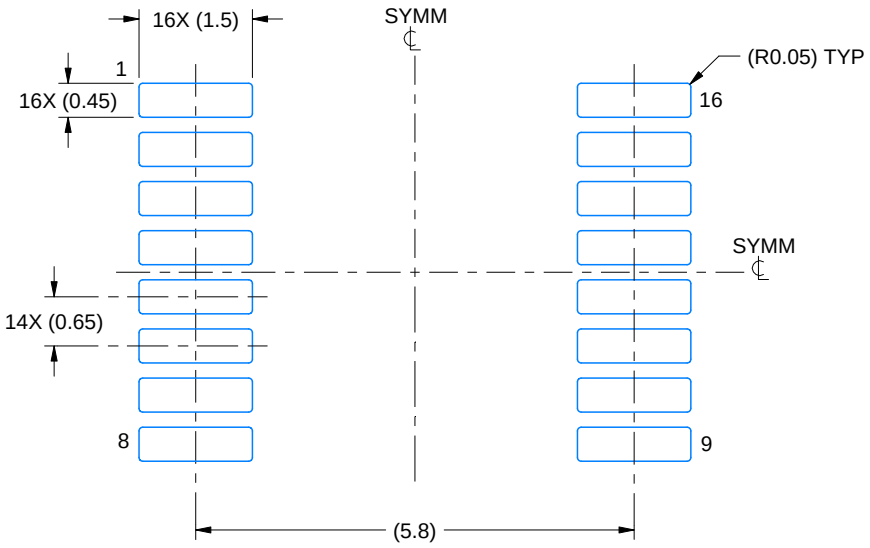
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

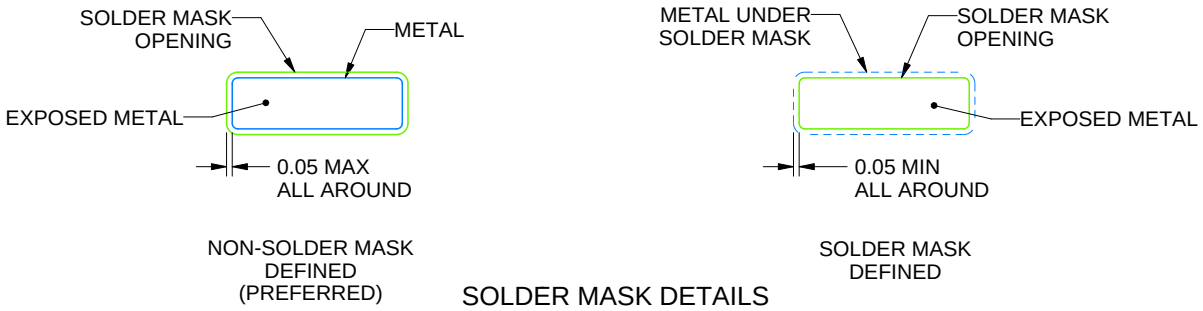


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

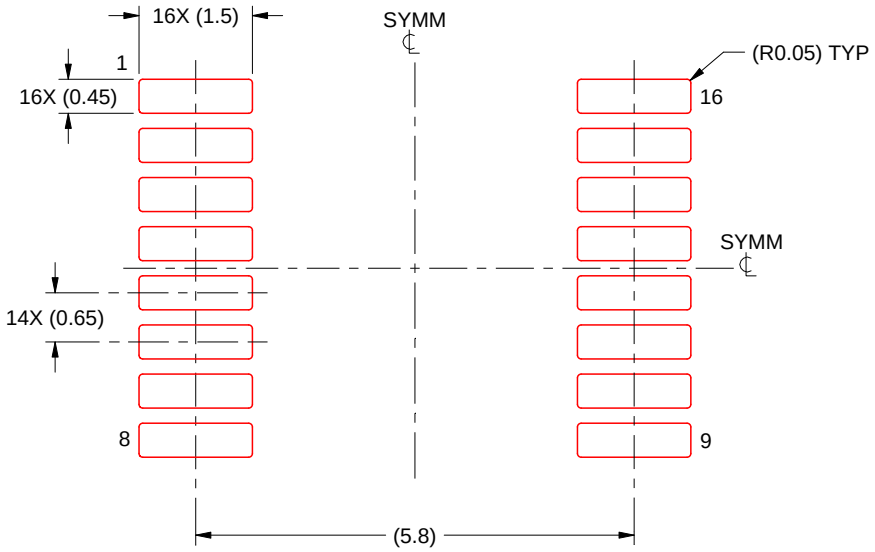


SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

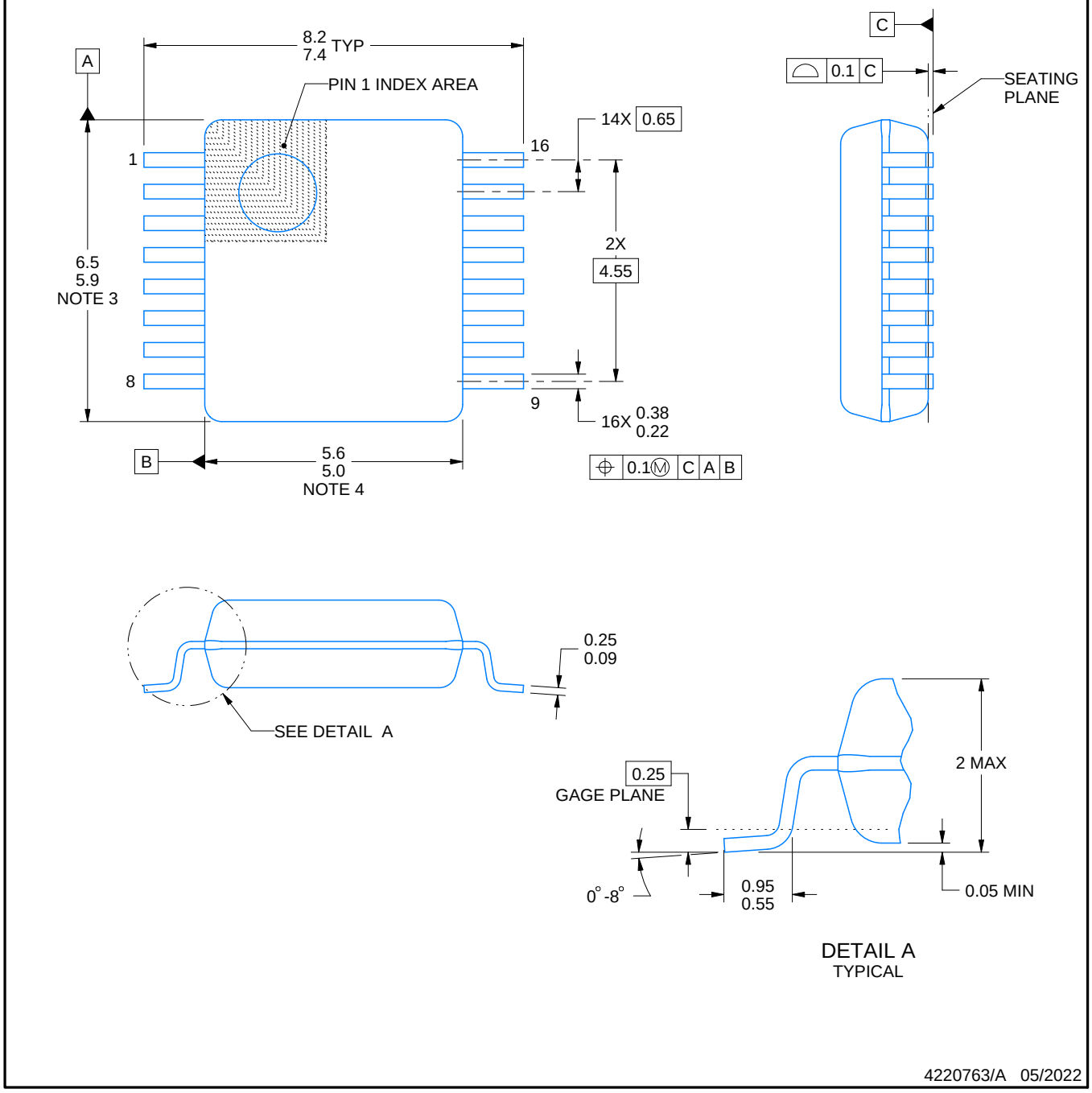
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DB0016A

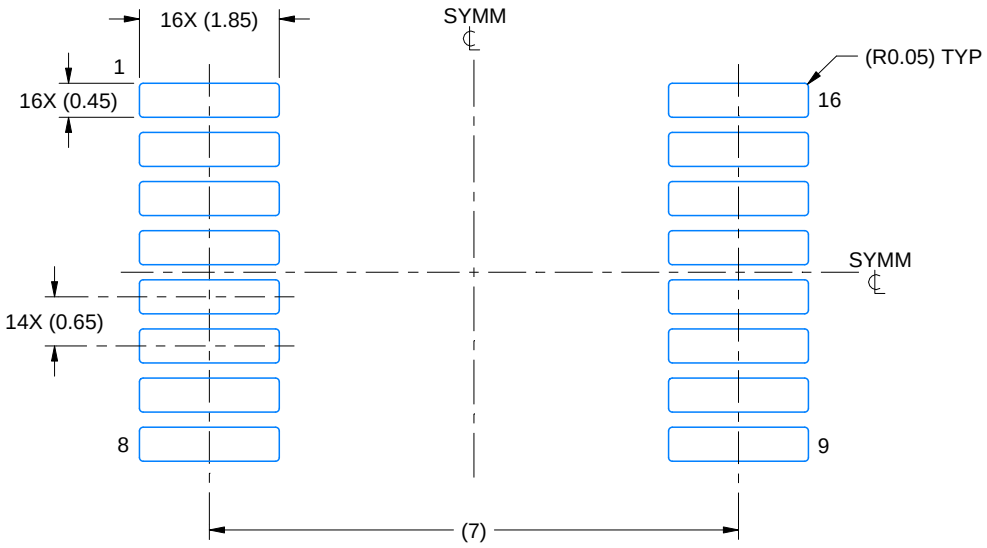
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

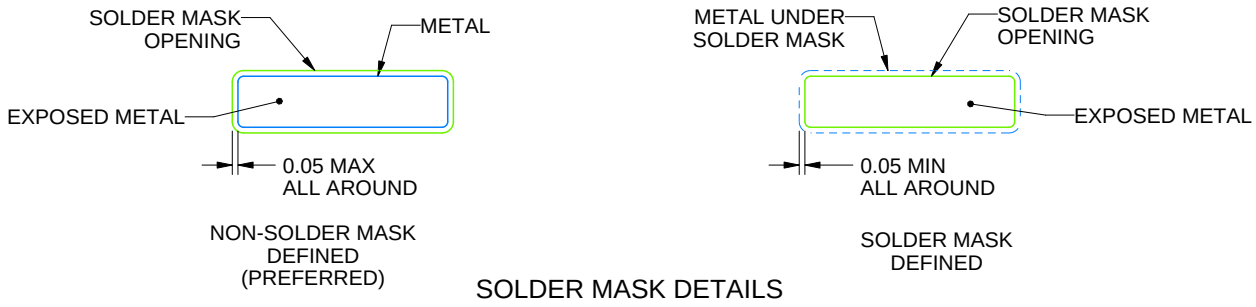


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

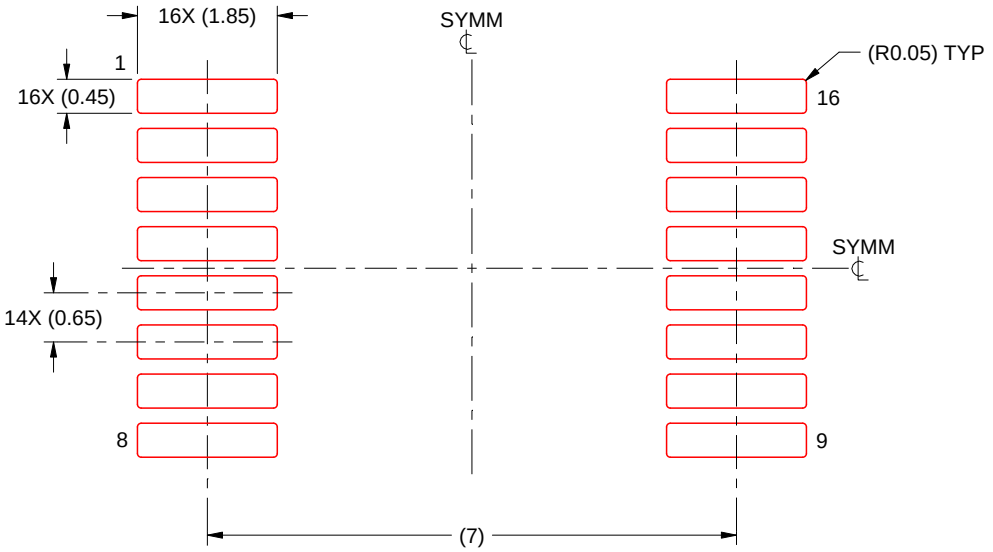


SOLDER MASK DETAILS

4220763/A 05/2022

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

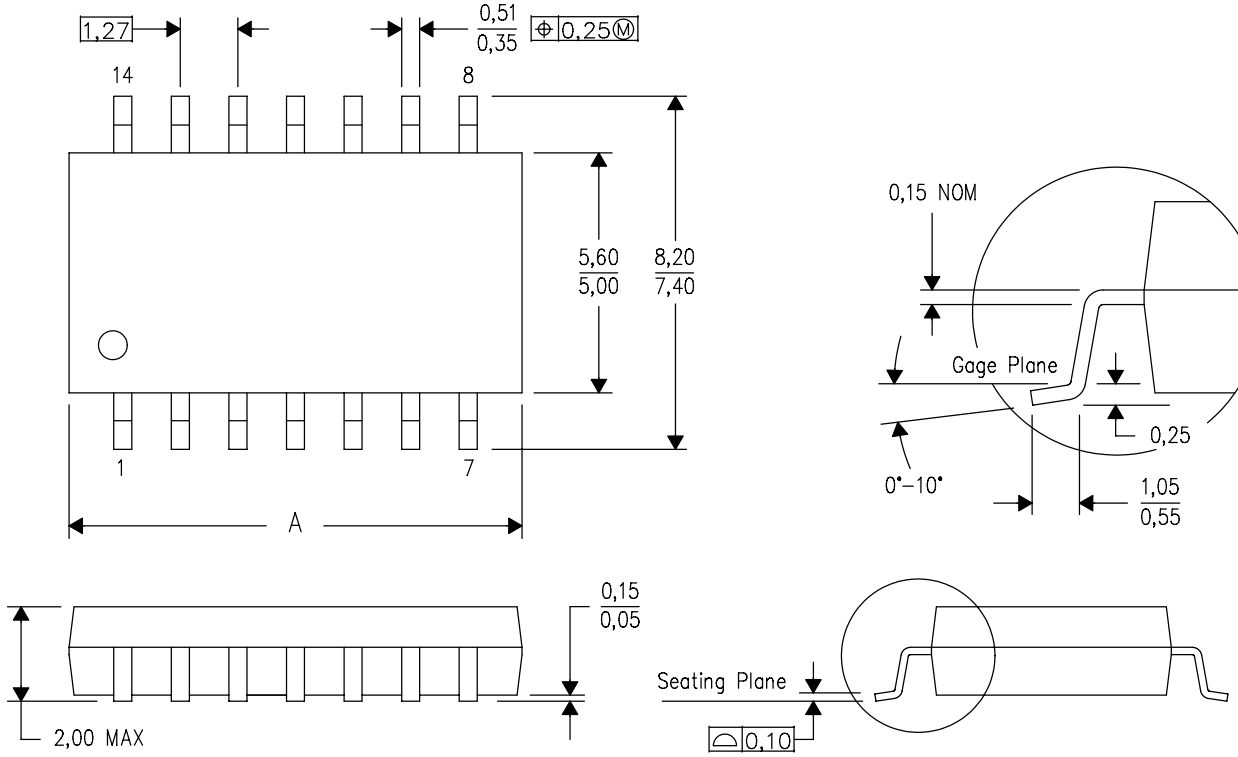
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



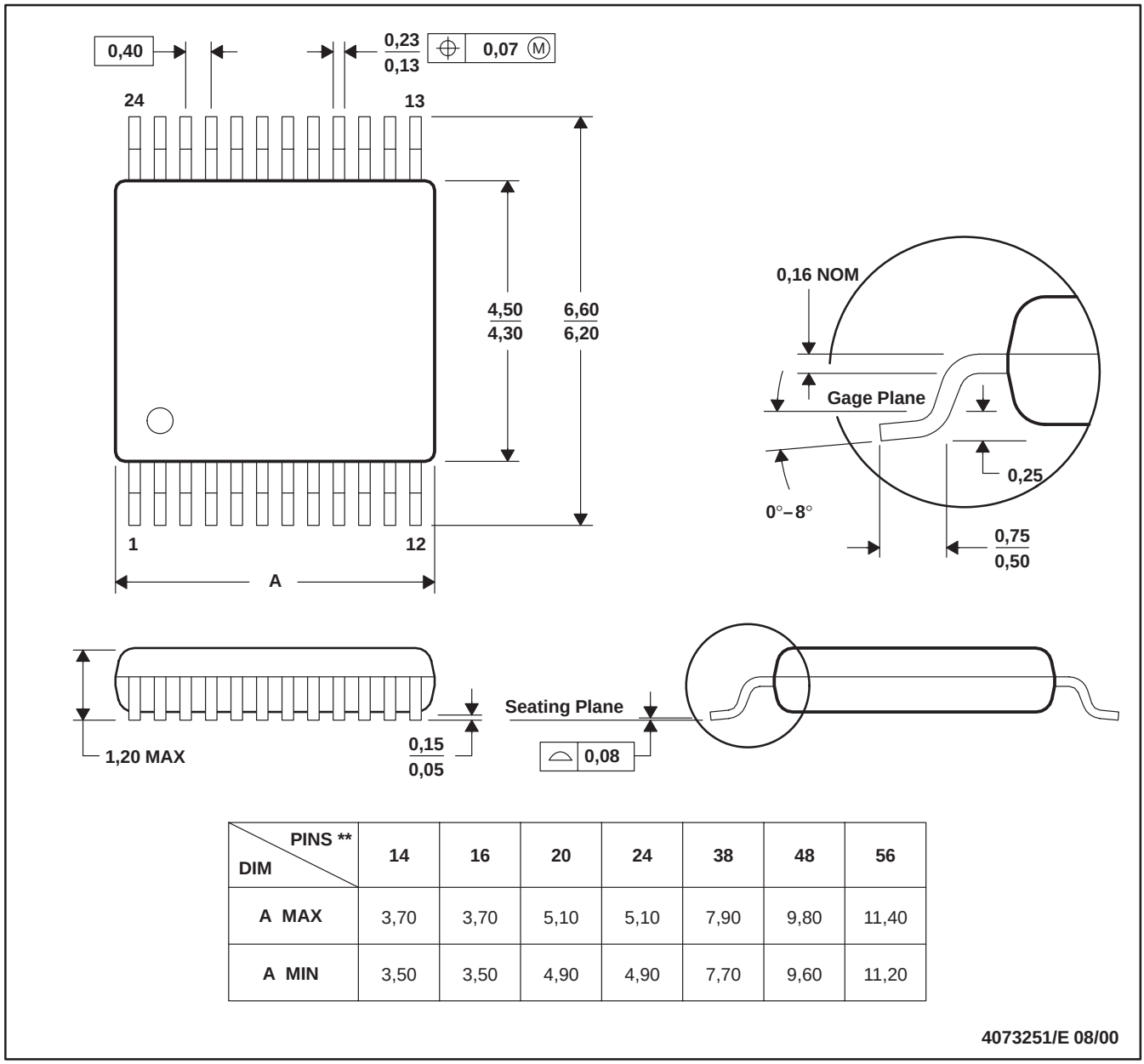
DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN

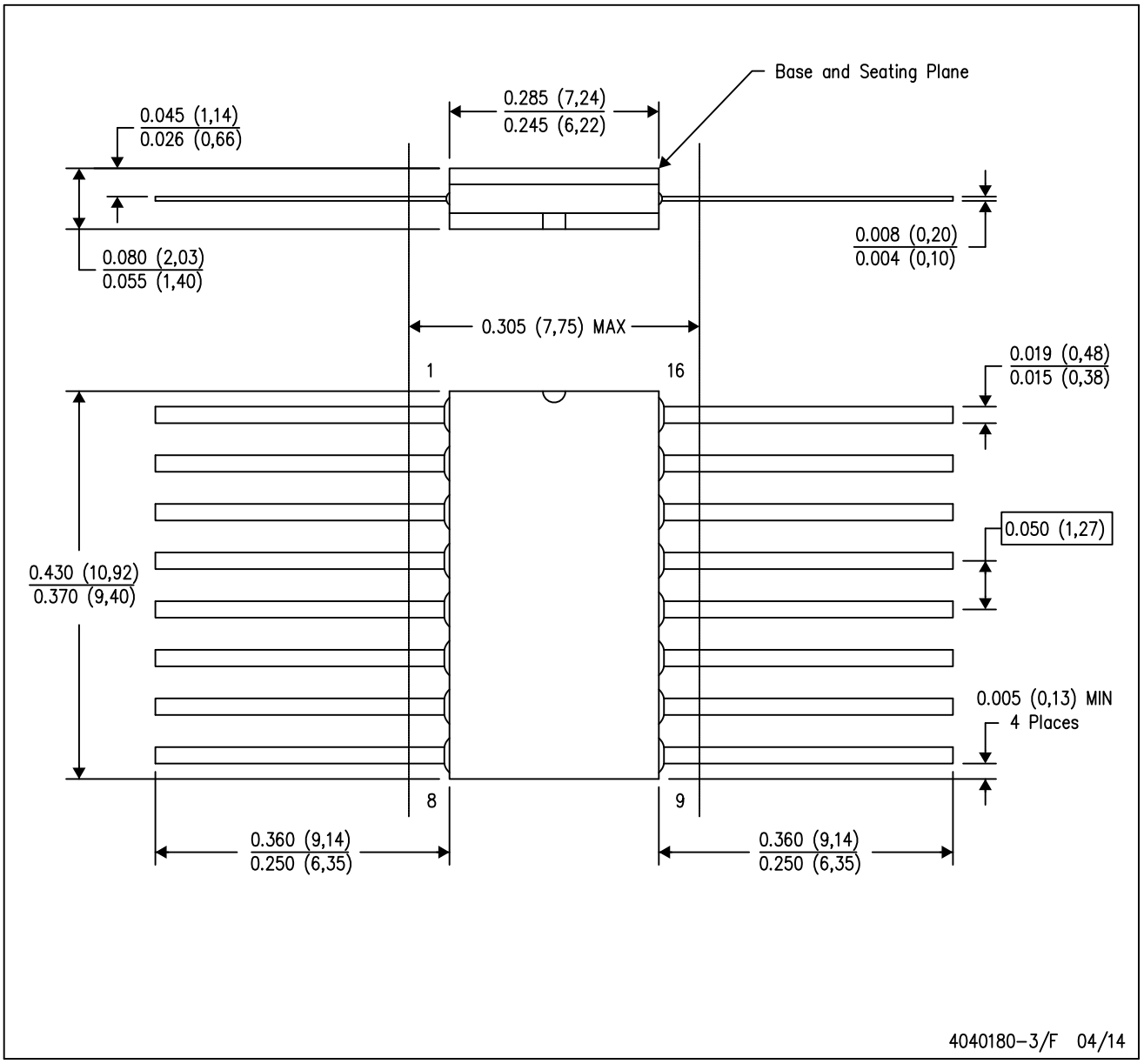


DIM \ PINS **	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

W (R–GDFP–F16) CERAMIC DUAL FLATPACK



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

GENERIC PACKAGE VIEW

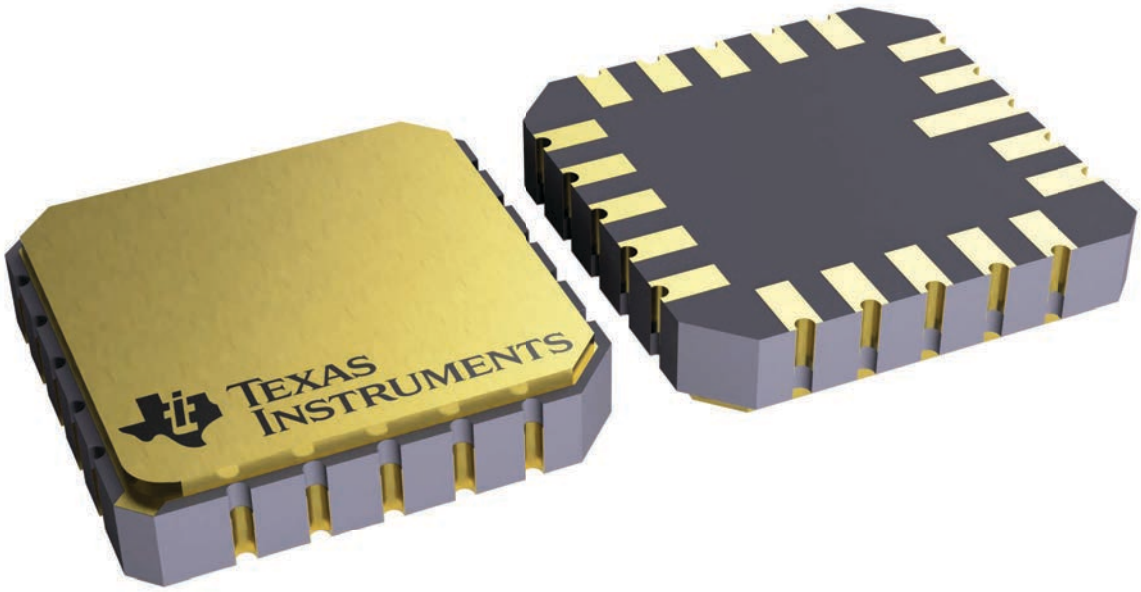
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

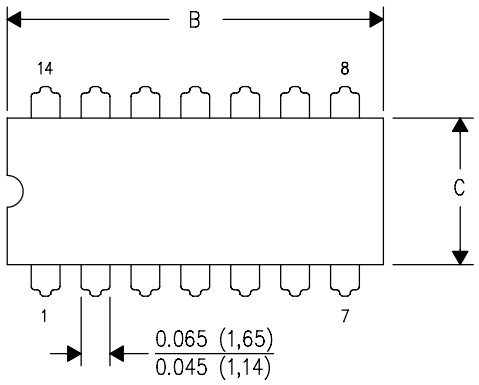


4229370VA\

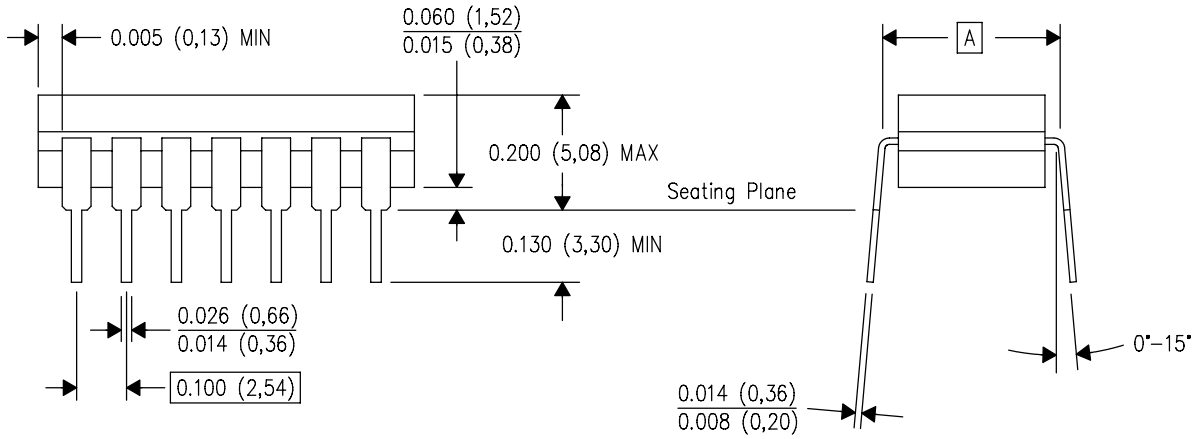
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



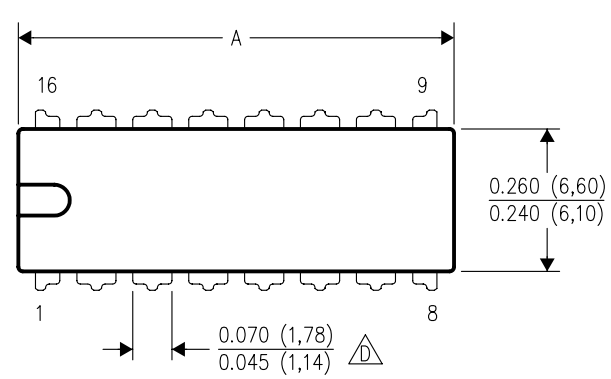
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

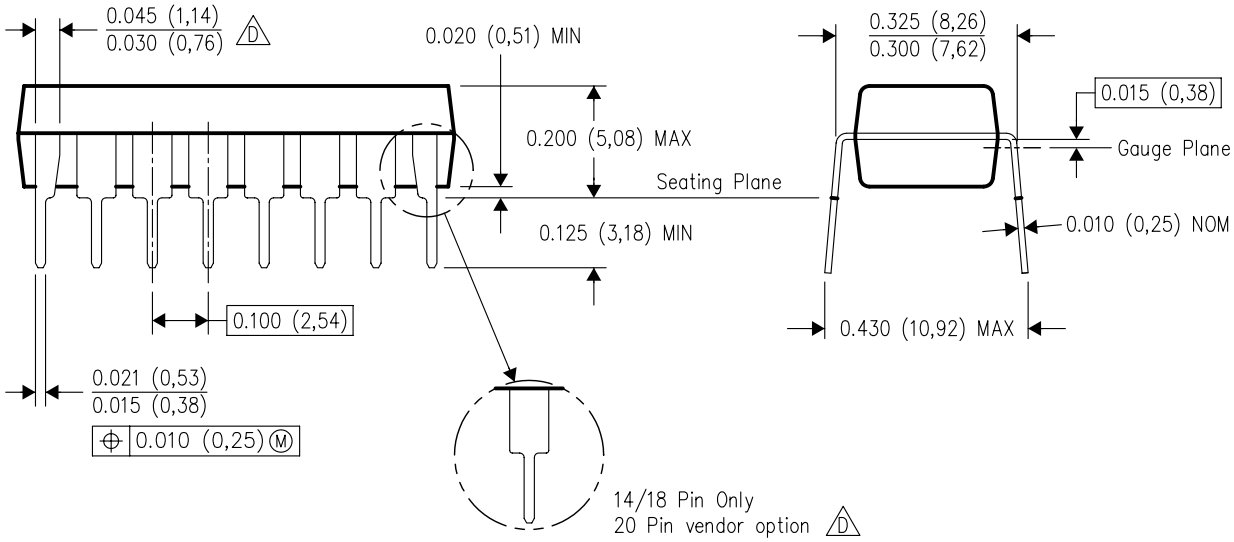
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



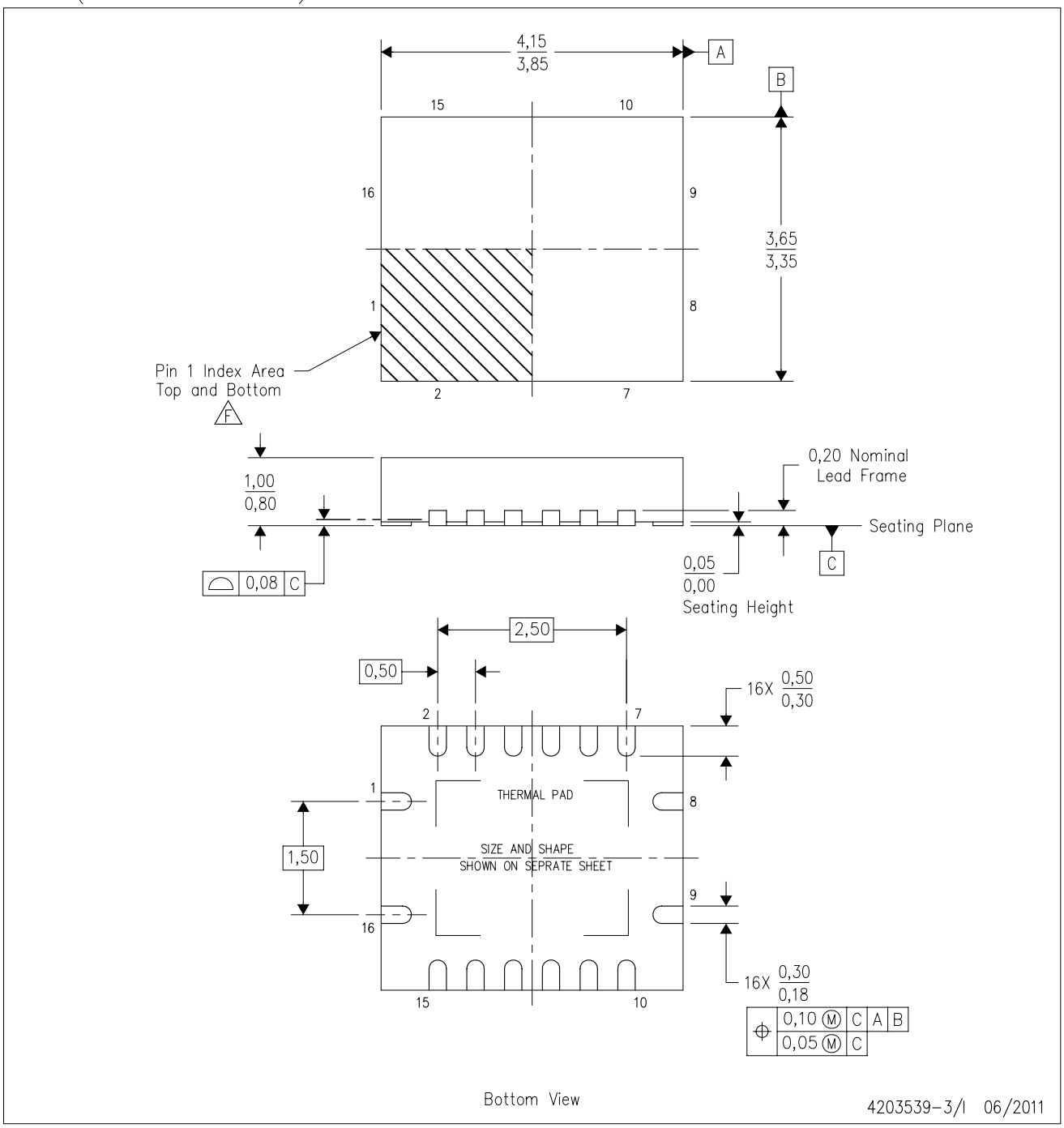
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

RGY (R–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No–Lead) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
G. Package complies to JEDEC MO–241 variation BA.

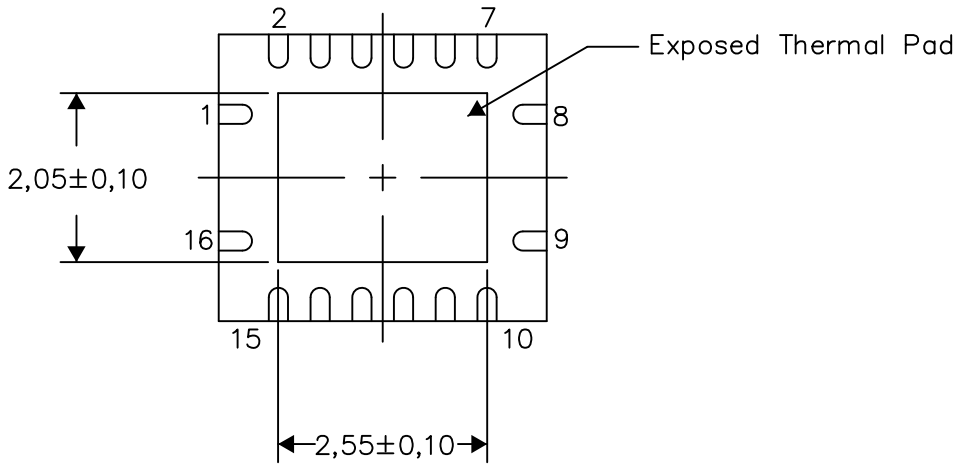
RGY (R–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



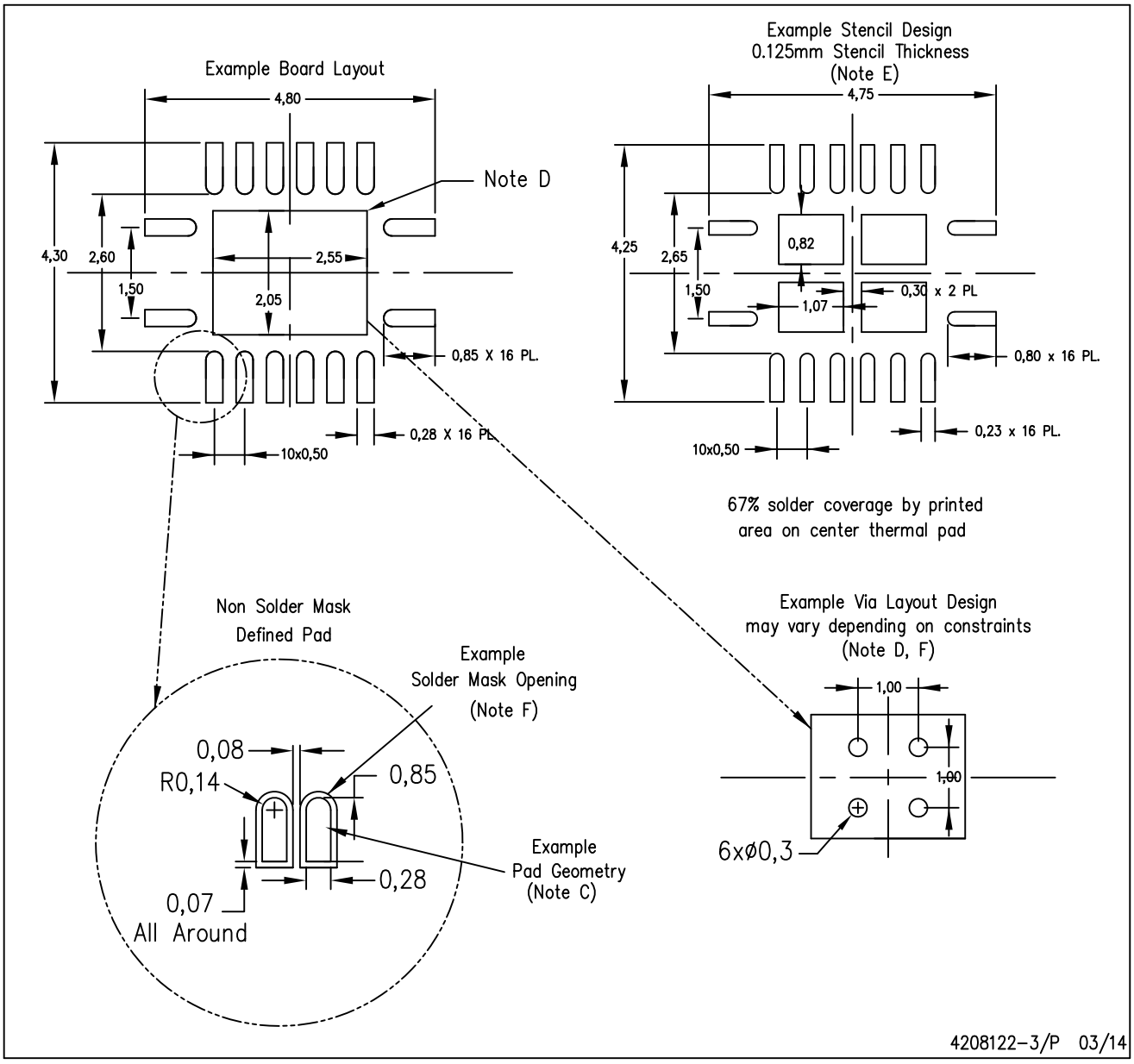
Bottom View

Exposed Thermal Pad Dimensions

4206353–3/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (R–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat–Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http: //www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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